

Figure 2a

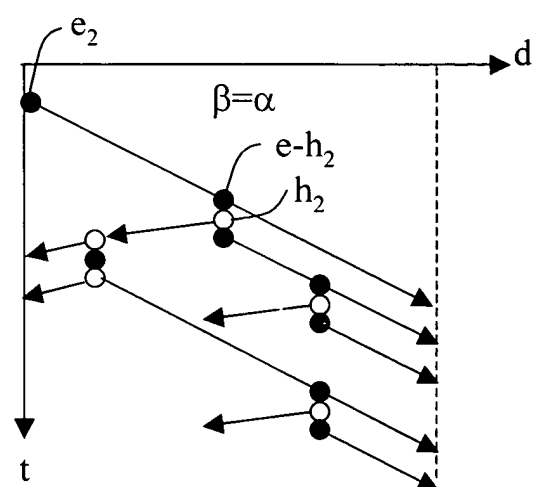


Figure 2b

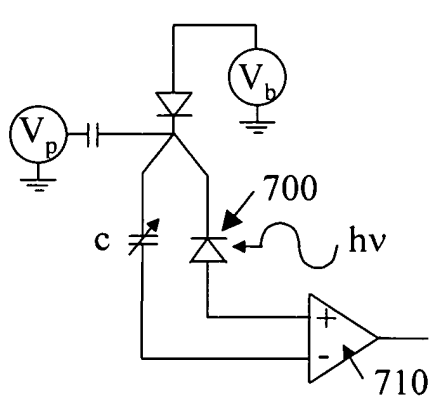


Figure 7a

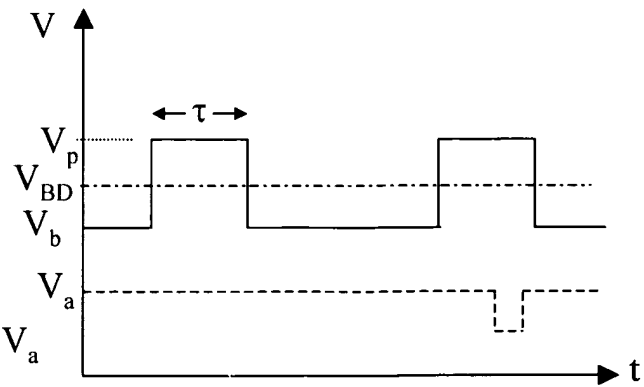
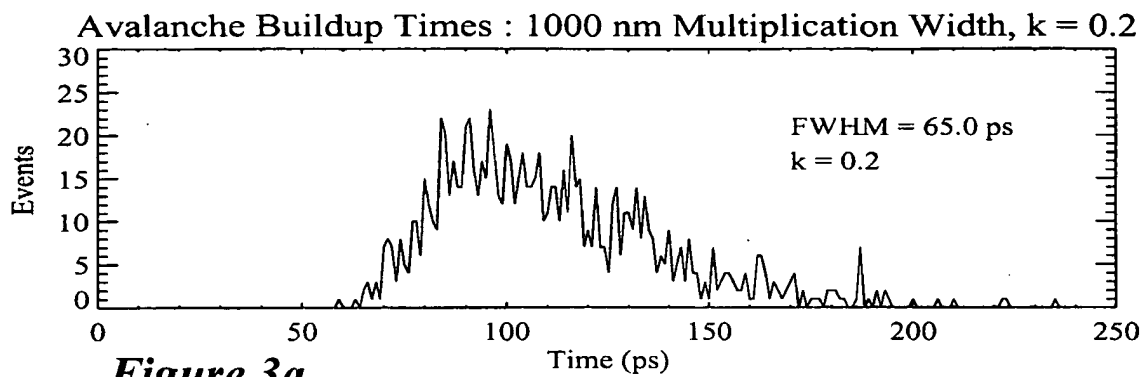
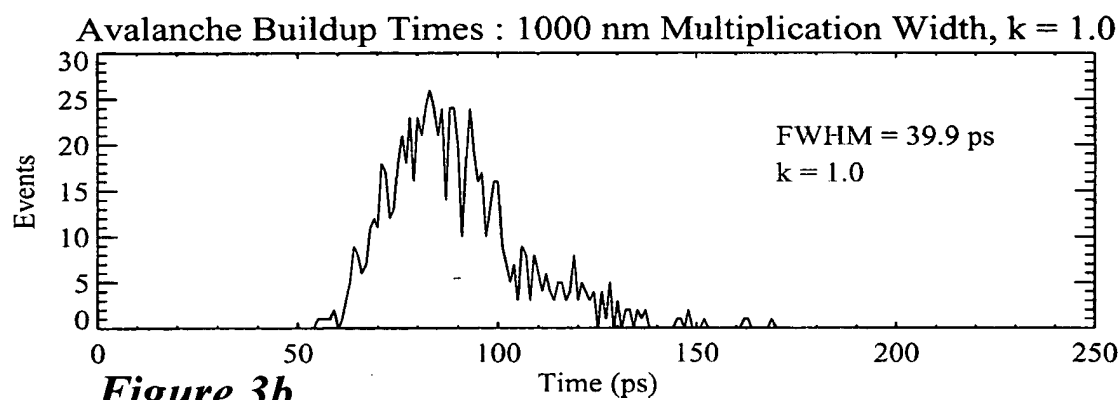


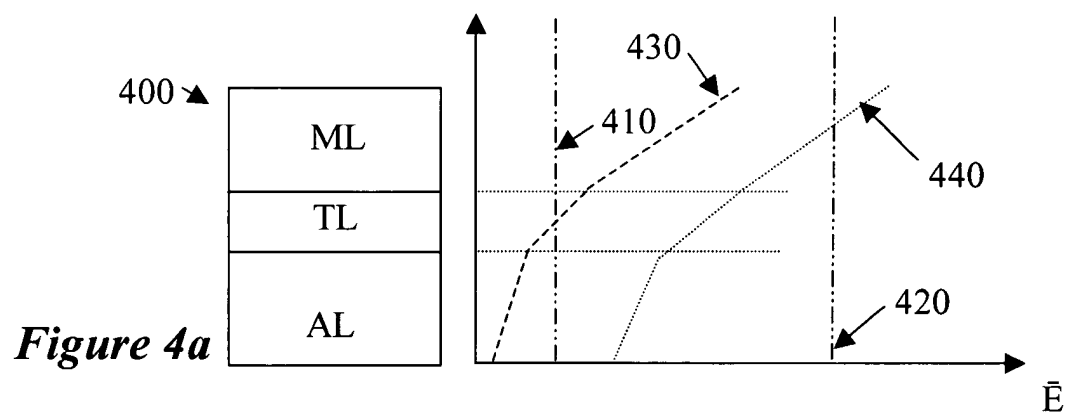
Figure 7b



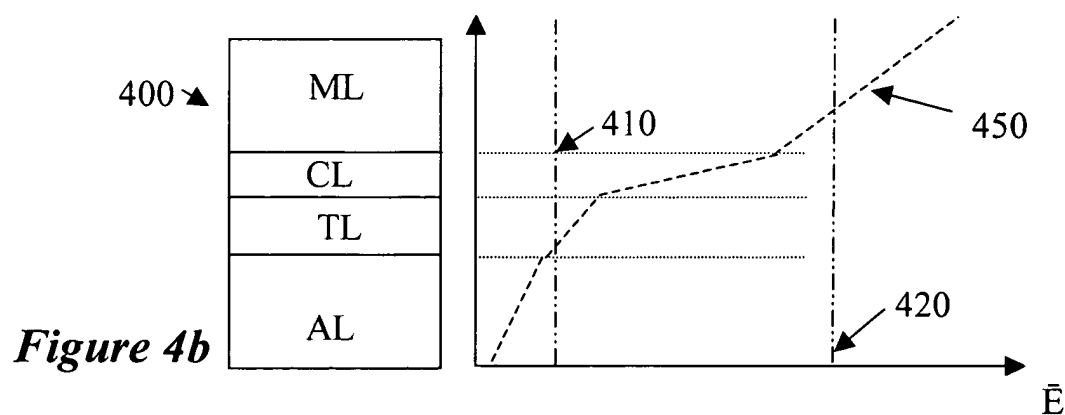
**Figure 3a**



**Figure 3b**



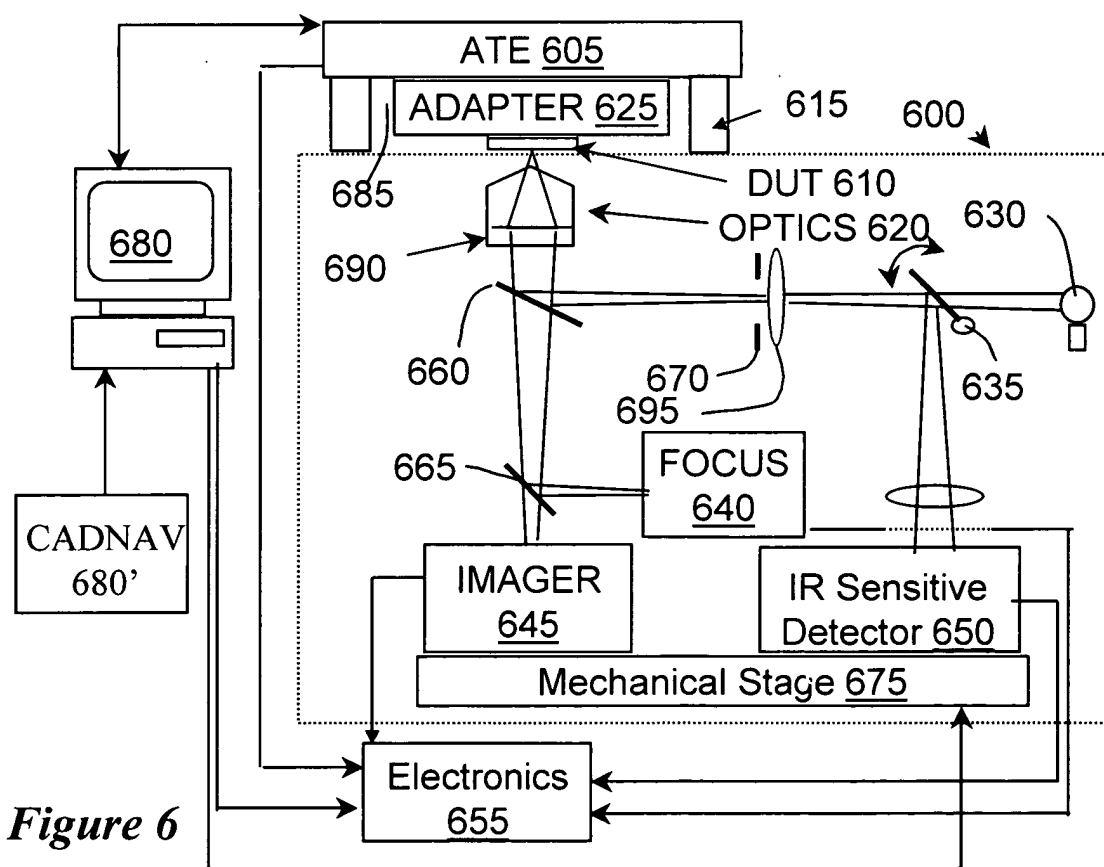
**Figure 4a**



**Figure 4b**

580 Metallization Contact Layer
570 $p^+$ -InP Layer
560 $i$ -InP Multiplication Layer
550 $n$ -InP Field Control Layer
540 $n$ -InGaAsP Grading Layer
530 $n$ -InGaAs or $n$ -InGaAsP Absorber
520 $i$ -InGaAs or $i$ -InGaAsP Absorber
510 $n^+$ -InP Buffer Layer
500 $n^+$ -InP Substrate

**Figure 5**



**Figure 6**